

L Number	Hits	Search Text	DB	Time stamp
1	174446	438/\$.ccls. or 702/\$.ccls. or 700/29-31,46,52,93,95-97,108-110,117,119,121-123,160,174-178.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/05 19:17
3	98705	(438/\$.ccls. or 702/\$.ccls. or 700/29-31,46,52,93,95-97,108-110,117,119,121-123,160,174-178.ccls.) and ((semi-conductor or (semi adj conductor) or semiconductor or wafer or (integrated adj (circuit or chip)) or IC) with (manufactur\$3 or product\$3 or fabricat\$3 or process\$3))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/05 20:00
4	1596	((infineon adj technologies).as.	USPAT; US-PGPUB	2003/10/05 19:19
5	0	((infineon adj technologies).as.) and (qualification adj procedure)	USPAT; US-PGPUB	2003/10/05 19:31
6	0	((infineon adj technologies).as.) and (tool adj qualification)	USPAT; US-PGPUB	2003/10/05 19:22
7	0	((infineon adj technologies).as.) and ((in-line or on-line or equipment or tool\$3 or in-situ or tool-set) with (qualification or qualify\$3))	USPAT; US-PGPUB	2003/10/05 19:24
8	0	((infineon adj technologies).as.) and ((in-line or on-line or equipment or tool\$3 or in-situ or tool-set) same (qualification or qualify\$3))	USPAT; US-PGPUB	2003/10/05 19:24
9	92	((438/\$.ccls. or 702/\$.ccls. or 700/29-31,46,52,93,95-97,108-110,117,119,121-123,160,174-178.ccls.) and ((semi-conductor or (semi adj conductor) or semiconductor or wafer or (integrated adj (circuit or chip)) or IC) with (manufactur\$3 or product\$3 or fabricat\$3 or process\$3))) and ((in-line or on-line or equipment or tool\$3 or in-situ or tool-set) same (qualification or qualify\$3))	USPAT; US-PGPUB	2003/10/05 19:25
10	64	((438/\$.ccls. or 702/\$.ccls. or 700/29-31,46,52,93,95-97,108-110,117,119,121-123,160,174-178.ccls.) and ((semi-conductor or (semi adj conductor) or semiconductor or wafer or (integrated adj (circuit or chip)) or IC) with (manufactur\$3 or product\$3 or fabricat\$3 or process\$3))) and ((in-line or on-line or equipment or tool\$3 or in-situ or tool-set) with (qualification or qualify\$3))	USPAT; US-PGPUB	2003/10/05 19:25
11	3	((infineon adj technologies).as.) and (qualification)	USPAT; US-PGPUB	2003/10/05 20:00
12	0	((infineon adj technologies).as.) and ((equipment or tool) with productivity)	USPAT; US-PGPUB	2003/10/05 19:39
13	2	((infineon adj technologies).as.) and ((equipment or tool) with quality)	USPAT; US-PGPUB	2003/10/05 19:39
14	10	((infineon adj technologies).as.) and (quality adj control)	USPAT; US-PGPUB	2003/10/05 19:59
15	1	((infineon adj technologies).as.) and (APC or (advanced adj process))	USPAT; US-PGPUB	2003/10/05 19:59
17	50	((438/\$.ccls. or 702/\$.ccls. or 700/29-31,46,52,93,95-97,108-110,117,119,121-123,160,174-178.ccls.) and ((semi-conductor or (semi adj conductor) or semiconductor or wafer or (integrated adj (circuit or chip)) or IC) with (manufactur\$3 or product\$3 or fabricat\$3 or process\$3))) and ((tool with recipe) same (model\$4 or simulat\$4))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/05 20:06
18	1032	((438/\$.ccls. or 702/\$.ccls. or 700/29-31,46,52,93,95-97,108-110,117,119,121-123,160,174-178.ccls.) and ((semi-conductor or (semi adj conductor) or semiconductor or wafer or (integrated adj (circuit or chip)) or IC) with (manufactur\$3 or product\$3 or fabricat\$3 or process\$3))) and (tool with (set\$3 or prepar\$5 or format\$4 or initial\$4 or initialization))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/05 20:06
19	115	((438/\$.ccls. or 702/\$.ccls. or 700/29-31,46,52,93,95-97,108-110,117,119,121-123,160,174-178.ccls.) and ((semi-conductor or (semi adj conductor) or semiconductor or wafer or (integrated adj (circuit or chip)) or IC) with (manufactur\$3 or product\$3 or fabricat\$3 or process\$3))) and ((tool with (set\$3 or prepar\$5 or format\$4 or initial\$4 or initialization)) same (model\$4 or simulat\$4))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/05 20:06

20	63	((438/\$.ccls. or 702/\$.ccls. or 700/29-31,46,52,93,95-97,108-110,117,119,121-123,160,174-178.ccls.) and ((semi-conductor or (semi adj conductor) or semiconductor or wafer or (integrated adj (circuit or chip)) or IC) with (manufactur\$3 or product\$3 or fabricat\$3 or process\$3))) and (((tool\$3 or equipment) with recipe) same (model\$4 or simulat\$4))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/05 21:09
21	198	((438/\$.ccls. or 702/\$.ccls. or 700/29-31,46,52,93,95-97,108-110,117,119,121-123,160,174-178.ccls.) and ((semi-conductor or (semi adj conductor) or semiconductor or wafer or (integrated adj (circuit or chip)) or IC) with (manufactur\$3 or product\$3 or fabricat\$3 or process\$3))) and (((tool\$3 or equipment) with (set\$3 or prepar\$5 or format\$4 or initial\$4 or initialization)) same (model\$4 or simulat\$4))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/05 20:15
22	18127	((438/\$.ccls. or 702/\$.ccls. or 700/29-31,46,52,93,95-97,108-110,117,119,121-123,160,174-178.ccls.) and ((semi-conductor or (semi adj conductor) or semiconductor or wafer or (integrated adj (circuit or chip)) or IC) with (manufactur\$3 or product\$3 or fabricat\$3 or process\$3))) and (((maintenanc\$3 or calibrat\$4) with (tool\$3 or equipment)) or clean\$3 or (replac\$5 with (item or pad)) or (condition\$3 with pad) or (alignment with accuracy) or (exposure adj dose))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/05 20:10
23	20	((438/\$.ccls. or 702/\$.ccls. or 700/29-31,46,52,93,95-97,108-110,117,119,121-123,160,174-178.ccls.) and ((semi-conductor or (semi adj conductor) or semiconductor or wafer or (integrated adj (circuit or chip)) or IC) with (manufactur\$3 or product\$3 or fabricat\$3 or process\$3))) and (((tool\$3 or equipment) with recipe) same (model\$4 or simulat\$4))) and (((438/\$.ccls. or 702/\$.ccls. or 700/29-31,46,52,93,95-97,108-110,117,119,121-123,160,174-178.ccls.) and ((semi-conductor or (semi adj conductor) or semiconductor or wafer or (integrated adj (circuit or chip)) or IC) with (manufactur\$3 or product\$3 or fabricat\$3 or process\$3))) and (((maintenanc\$3 or calibrat\$4) with (tool\$3 or equipment)) or clean\$3 or (replac\$5 with (item or pad)) or (condition\$3 with pad) or (alignment with accuracy) or (exposure adj dose)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/05 20:16
24	1013	((438/\$.ccls. or 702/\$.ccls. or 700/29-31,46,52,93,95-97,108-110,117,119,121-123,160,174-178.ccls.) and ((semi-conductor or (semi adj conductor) or semiconductor or wafer or (integrated adj (circuit or chip)) or IC) with (manufactur\$3 or product\$3 or fabricat\$3 or process\$3))) and ((set\$3 or prepar\$5 or format\$4 or initial\$4 or initialization) with (model\$4 or simulat\$4))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/05 20:16

25	23	(((438/\$.ccls. or 702/\$.ccls. or 700/29-31,46,52,93,95-97,108-110,117,119,121-123,160,174-178.ccls.) and ((semi-conductor or (semi adj conductor) or semiconductor or wafer or (integrated adj (circuit or chip)) or IC) with (manufactur\$3 or product\$3 or fabricat\$3 or process\$3))) and (((tool\$3 or equipment) with recipe) same (model\$4 or simulat\$4))) and (((438/\$.ccls. or 702/\$.ccls. or 700/29-31,46,52,93,95-97,108-110,117,119,121-123,160,174-178.ccls.) and ((semi-conductor or (semi adj conductor) or semiconductor or wafer or (integrated adj (circuit or chip)) or IC) with (manufactur\$3 or product\$3 or fabricat\$3 or process\$3))) and ((set\$3 or prepar\$5 or format\$4 or initial\$4 or initialization) with (model\$4 or simulat\$4))) and (((438/\$.ccls. or 702/\$.ccls. or 700/29-31,46,52,93,95-97,108-110,117,119,121-123,160,174-178.ccls.) and ((semi-conductor or (semi adj conductor) or semiconductor or wafer or (integrated adj (circuit or chip)) or IC) with (manufactur\$3 or product\$3 or fabricat\$3 or process\$3))) and (((maintenanc\$3 or calibrat\$4) with (tool\$3 or equipment)) or clean\$3 or (replac\$5 with (item or pad)) or (condition\$3 with pad) or (alignment with accuracy) or (exposure adj dose))))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/05 20:16
26	13	(((438/\$.ccls. or 702/\$.ccls. or 700/29-31,46,52,93,95-97,108-110,117,119,121-123,160,174-178.ccls.) and ((semi-conductor or (semi adj conductor) or semiconductor or wafer or (integrated adj (circuit or chip)) or IC) with (manufactur\$3 or product\$3 or fabricat\$3 or process\$3))) and (((tool\$3 or equipment) with recipe) same (model\$4 or simulat\$4))) and (((438/\$.ccls. or 702/\$.ccls. or 700/29-31,46,52,93,95-97,108-110,117,119,121-123,160,174-178.ccls.) and ((semi-conductor or (semi adj conductor) or semiconductor or wafer or (integrated adj (circuit or chip)) or IC) with (manufactur\$3 or product\$3 or fabricat\$3 or process\$3))) and ((set\$3 or prepar\$5 or format\$4 or initial\$4 or initialization) with (model\$4 or simulat\$4))) and (((438/\$.ccls. or 702/\$.ccls. or 700/29-31,46,52,93,95-97,108-110,117,119,121-123,160,174-178.ccls.) and ((semi-conductor or (semi adj conductor) or semiconductor or wafer or (integrated adj (circuit or chip)) or IC) with (manufactur\$3 or product\$3 or fabricat\$3 or process\$3))) and (((maintenanc\$3 or calibrat\$4) with (tool\$3 or equipment)) or clean\$3 or (replac\$5 with (item or pad)) or (condition\$3 with pad) or (alignment with accuracy) or (exposure adj dose)))) and ((model\$4 or simulat\$4) with control\$4 with (recipe or sequence))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/05 21:10